



CS98-106/7/8C

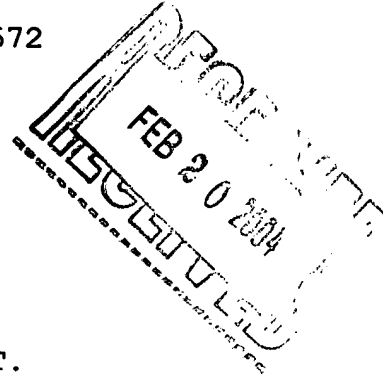
# 2813  
Application No. 09/817,473

January 20, 2004

TO: Commissioner of Patents  
P.O. Box 1435  
Alexandria, VA 22313-1450

FROM: George O. Saile, Reg. No. 19,572  
28 Davis Ave.  
Poughkeepsie, N.Y. 12603

SUBJECT: Serial #: 09/817,473  
File Date: 03/26/2001  
Inventor: YI, XU ET AL.  
Examiner: NGUYEN, THANH T.  
Art Unit: 2813  
Title: GAP FILLING PROCESS IN INTEGRATED  
CIRCUITS USING LOW DIELECTRIC CONSTANT  
MATERIALS



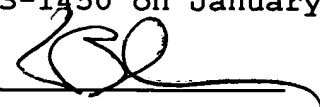
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FEB 10 2004  
TECHNOLOGY CENTER 280C

RESPONSE TO OFFICE ACTION

This is in response to the Office Action dated October 16, 2003, Paper No. 15. Please consider the following in regards to the above referenced application.

CERTIFICATE OF MAILING

I hereby certify that this correspondence is being deposited with the United States Postal Service as first class mail in an envelope addressed to: Commissioner of Patents, P.O. Box 1435, Alexandria, VA 22313-1450 on January 30, 2004.

Signature 

Date: 1/30/04

Stephen B. Ackerman, Reg. No. 37,761

TABLE OF CONTENTS:

Amendments to the Claims are reflected in the listing of claims which begins on page 3 of this paper.

Remarks begin on page 5 of this paper.

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